

20-3221 LOW VISCOSITY EPOXY POTTING AND ENCAPSULATING RESIN

DESCRIPTION:

20-3221 is a very low viscosity epoxy potting, casting and encapsulating resin system. 20-3221 is a filled system resulting in excellent dimensional stability and low shrinkage.

20-3221 offers outstanding physical, thermal and electrical insulation properties. It also provides excellent resistance to chemicals, moisture, solvents and environmental exposure.

20-3221 has been formulated for ease in handling. Its low viscosity aids in pouring, filling voids and air pockets. In addition, the fillers in 20-3221 have been dispersed to minimize any heavy settling.

TYPICAL SPECIFICATIONS:

Mix viscosity, @ 25 °C cps	6,000
Pot life, @ 25°C	
with Catalyst 30	4 Hours
with Catalyst 190	30 Minutes
Cure shrinkage, in/in	0.0018
Specific gravity, 25 ℃	1.12
Hardness, Shore D	88
Tensile strength, psi	7,500
Compressive strength, psi	16,000
Flexural strength, psi	12,500
Izod impact, ft-lb/in	0.30
Water absorption, @ 25℃, %	0.009
Machinability	Excellent
Thermal Expansion Coefficient/°F	28.5 x 10 ⁻⁶
Thermal Conductivity, W/m- °K	0.65

INSTRUCTIONS FOR USE:

- A. ROOM TEMPERATURE CURING WITH CATALYST 190:
 - 1. By weight, thoroughly mix 7 parts Catalyst 190 to 100 parts 20-3221 Resin.
 - 2. Pour and cure 12 hours at room temperature or accelerate with mild heat (80-90°F).
- B. HEAT CURING WITH CATALYST 30 (Recommended for higher operating temperature and physical property applications):
 - 1. By weight, thoroughly mix 12.5 parts Catalyst 30 to 100 parts 20-3221 Resin.
 - 2. Pour and cure according to one of the following recommended cure schedules:
 - a) $85 \degree C (185 \degree F)$ 3-4 hours b) $100 \degree C (212 \degree F)$ 2-3 hours

For optimum performance, an additional 2 hours @ 365 °F (185 °C) is recommended.



IMPORTANT:

EPOXIES, ETC. MAKES NO EXPRESS OR IMPLIED WARRANTIES OR MERCHANTABILITY, FITNESS OR OTHERWISE WITH RESPECT TO ITS PRODUCTS. The information in this brochure is based on data obtained by our own research and is considered reliable. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. The properties given are typical values and are not intended for use in preparing specifications. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

09/14